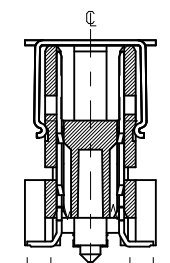
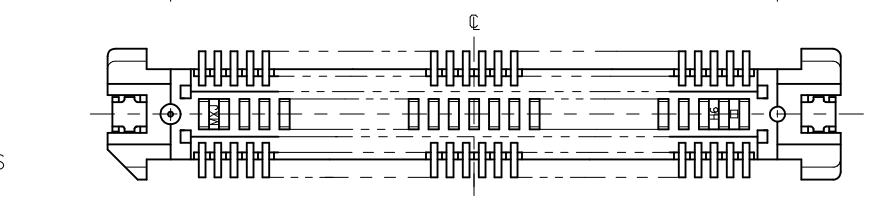
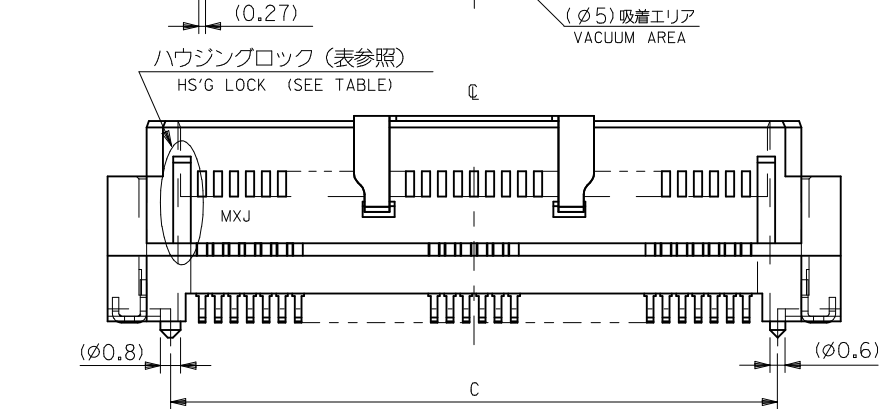
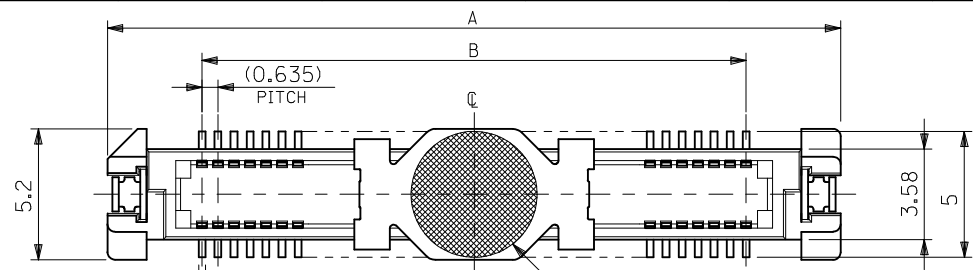
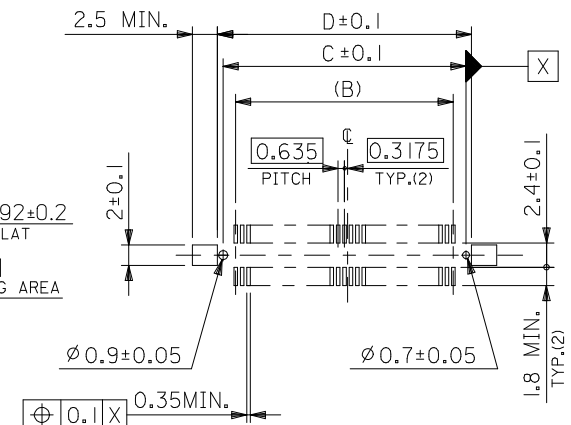


10 9 8 7 6 5 4 3 2 1



半田付け部詳細図
DETAIL FOR SOLDERING AREA



推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE:2-1)

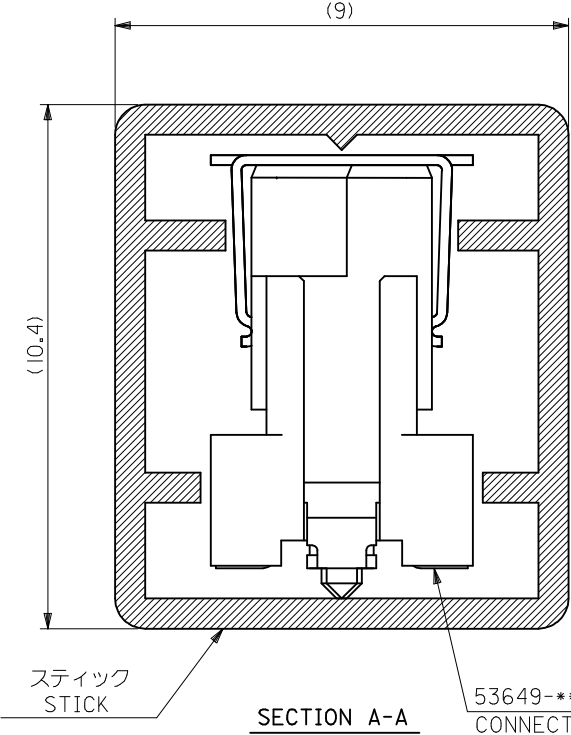
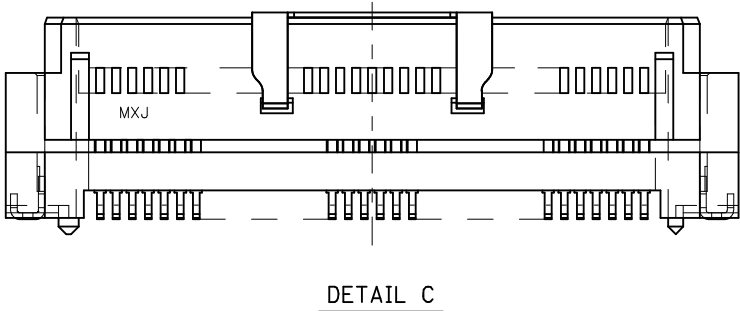
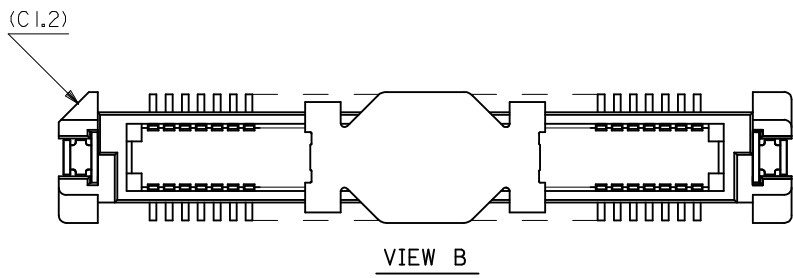
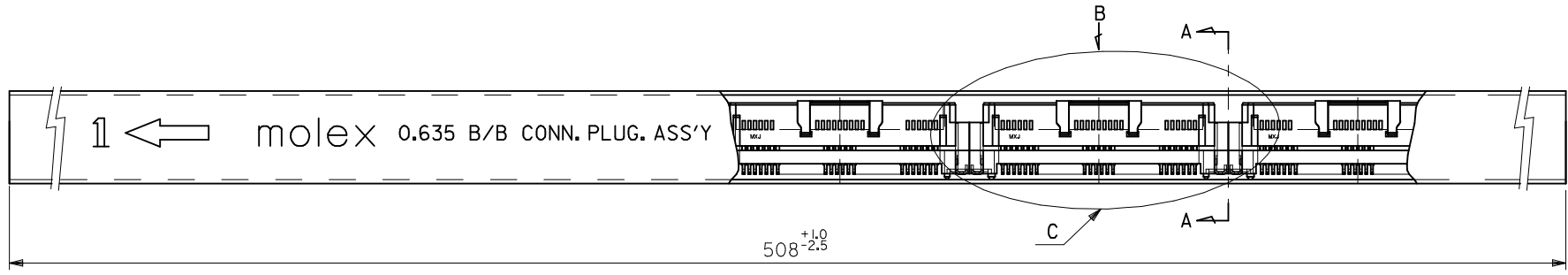
注) NOTES

- 1.材質 MATERIAL
ハウジング: ガラス入りPPS、茶色、UL94V-0
HOUSING: G.F.PPS, BROWN, UL94V-0
ターミナル: 銅合金 (t=0.2)
TERMINAL: COPPER ALLOY
フィッティングネイル: 銅合金 (t=0.2)
FITTING NAIL: COPPER ALLOY
吸着カバー: ステンレス (t=0.2)
VACUUM COVER: STAINLESS STEEL
- 2.メッキ仕様 PLATING
ターミナル TERMINAL
接点部 : 金メッキ 0.25 μmMIN.
CONTACT AREA: GOLD 0.25 μmMIN.
半田付け部 : 錫メッキ 1.0 μmMIN.
SOLDER TAIL AREA: TIN 1.0 μmMIN.
下地メッキ : ニッケルメッキ 1.5 μmMIN.
UNDER-PLATING: NICKEL 1.5 μmMIN.
- 3.テールのバラツキ寸法 TAIL COPLANARITY
テール平坦度は、0.1MAX. とする。
TAIL COPLANARITY TO BE 0.1MAX.
- 4.本製品は 53649-***2 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53649-***2

	47.42	46.32	43.815	51.32	—#—	53649-1475	53649-1472	140
無し NO	34.72	33.62	31.115	38.62	53649-1074	—#—	53649-1072	100
	28.37	27.27	24.765	32.27	53649-0874	53649-0875	53649-0872	80
有り YES	22.02	20.92	18.415	25.92	53649-0674	—#—	53649-0672	60
	15.67	14.57	12.065	19.57	53649-0474	53649-0475	53649-0472	40
	12.5	11.4	8.89	16.4	53649-0374	—#—	53649-0372	30
ハウジングロック HS'G LOCK	D	C	B	A	エンボス梱包 EMBOSSED PACKAGING	スティック梱包 STICK PACKAGING	製品番号 MATERIAL NO.	極数 CKT. NO.
							MODEL NO. 53649-***72	

REVISED EC NO: J2016-0892 DRAWN: Y. SHIDA 2016/02/22 CHK'D: K. TANAKA 03 2016/02/22 APP'R: K. MORIKAWA 2016/02/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	0.25 UNDER	UNDER	±0.03	DRAWN BY M. NABEI	DATE '04/02/25	TITLE 0.635 B/B CONN. PLUG HS'G COVER ASS'Y -LEAD FREE-			
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K. TOJO	DATE '04/02/25				
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE '04/02/25				DOCUMENT NO. SD-53649-004
	1.0 OVER	10 UNDER	±0.2	SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	10 OVER	30 UNDER	±0.25						
	30 OVER		±0.3						
	ANGULAR	±3 °							
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								
	SIZE A3								

9 8 7 6 5 4 3 2 1



- NOTES.
1. スティック両端はキャップ止め。
BOTH ENDS WITH CAPS.
 2. 量産対応済の極数のについては、SD-53649-004を参照下さい。
SEE SD-53649-004 FOR AVAILABLE ITEMS.
 3. 本製品は53649-***5の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53649-***5

9	53649-1475	140
14	53649-0875	80
24	53649-0475	40
極包数量 QUANTITY	MATERIAL NO.	極数 CIRCUIT
MODEL NO.		53649-006

MATERIAL
材料
スティック : ポリ塩化ビニル
STICK : P.V.C.

REVISED EC NO: J2016-0892 DRWN: Y. SHIDA 2016/02/22 CHKD: K. TANAKA03 2016/02/22 APPR: K. MORIKAWA 2016/02/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	TITLE 0.635 B/B CONN. PLUG HSG ASS'Y STICK PACKAGE -LEAD FREE- molex DOCUMENT NO. SD-53649-006 SHEET NO. 1 OF 1
	0.25 UNDER	UNDER	±---	DRAWN BY M. NABEI	DATE '04/2/25	THIRD ANGLE PROJECTION	
	0.25 OVER	0.5 UNDER	±---	CHECKED BY K. TOJO	DATE '04/2/25		
	0.5 OVER	1.0 UNDER	±---	APPROVED BY M. SASAO	DATE '04/2/25		
	1.0 OVER	30 UNDER	±---	MATERIAL NO.	SEE TABLE		
30 OVER		±---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
ANGULAR		±--- °	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		